

SOT617-17

HVQFN32, plastic, thermal enhanced very thin quad flatpack; no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.9 mm body

8 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN32
Package type industry code	HVQFN32
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-01-2016
Manufacturer package code	98ASA00473D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	5	-	mm
package width	-	5	-	mm
package height	-	0.9	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



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2 Package outline

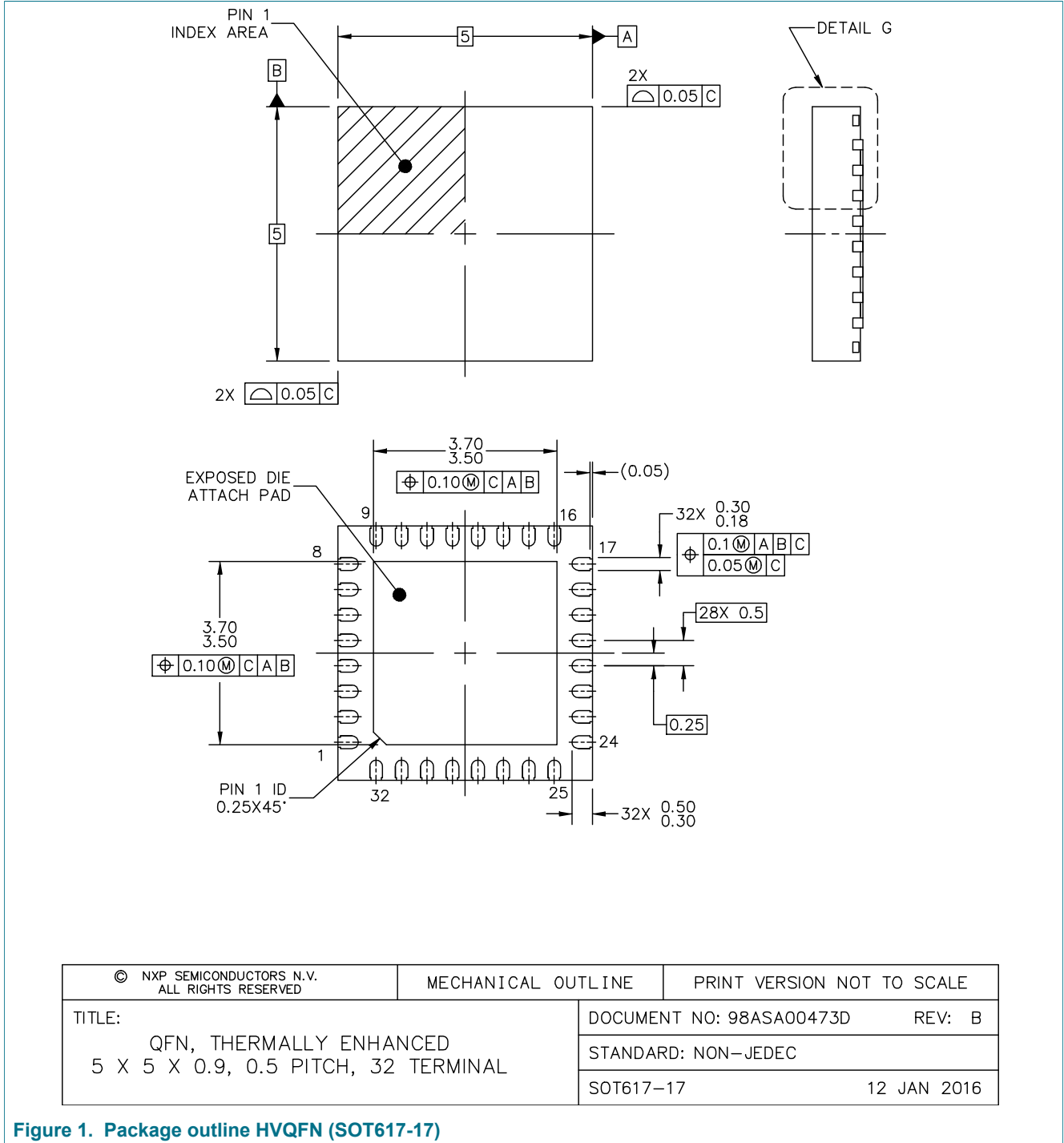
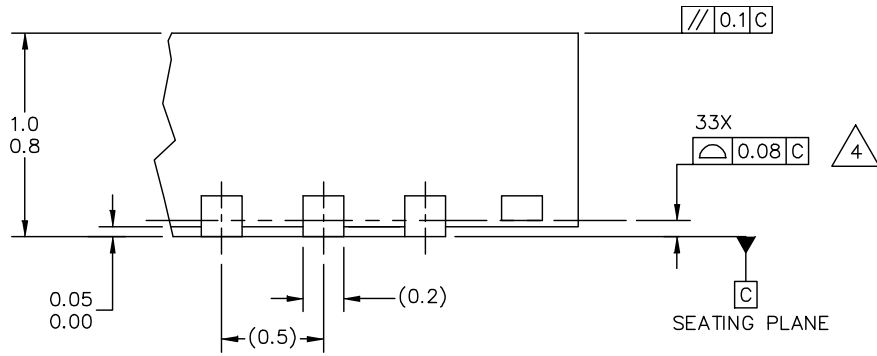


Figure 1. Package outline HVQFN (SOT617-17)

HVQFN32, plastic, thermal enhanced very thin quad flatpack; no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.9 mm body




DETAIL G
VIEW ROTATED 90°CW

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TITLE: QFN, THERMALLY ENHANCED 5 X 5 X 0.9, 0.5 PITCH, 32 TERMINAL	DOCUMENT NO: 98ASA00473D	REV: B
	STANDARD: NON-JEDEC	
	SOT617-17	12 JAN 2016

Figure 2. Package outline dt1 HVQFN (SOT617-17)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 3. Package outline note HVQFN (SOT617-17)

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3 Legal information

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